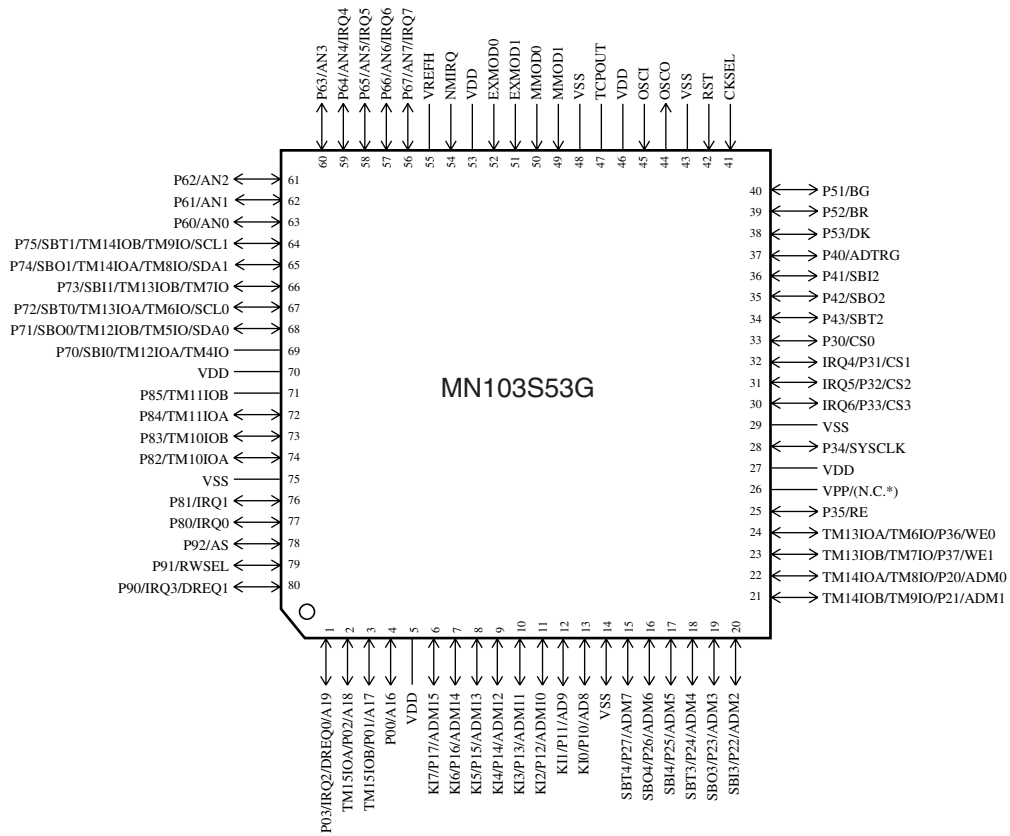


□ MN103S53G

Type	MN103S53G (under development)	
Command ROM (×64-bit)	128 K-byte	
Data RAM (×32-bit)	12 K-byte	
Package	LQFP80-P-1414A *Pb-free	
Minimum Instruction Execution Time	25.0 ns (at 3.0 V to 3.6 V, 40 MHz)	
Interrupts	<ul style="list-style-type: none"> • RESET • IRQ × 8 • NMI • Timer × 28 • SIF × 10 • I²C × 2 • DMA × 6 • WDT • A/D • System error 	
Timer Counter	<p>8-bit timer × 10</p> <ul style="list-style-type: none"> Reload-down count Cascade connection possible (usable as a 16-bit to 32-bit timer) <p>16-bit timer × 6</p> <ul style="list-style-type: none"> Up-down count Input capture function PWM generating function Compare/capture register 2-ch. <p>Watchdog timer × 1</p>	
DMA Controller	<p>Number of channels: 2</p> <p>Unit of transfer: 8/16/32 bits</p> <p>Max. Transfer cycles: 65535</p> <p>Starting factor: external interrupt, timer factor, serial transmission/reception factor, I²C transmission/reception factor, external transmission request factor, A/D conversion finish, software factor</p> <p>Transfer method: 2-bus cycle transfer</p> <p>Addressing modes: fixed, increment, decrement</p> <p>Transfer modes: word transfer, burst transfer, intermittent transfer</p>	
Serial Interface	<p>UART/synchronous/multi-master I²C interface selective: 2</p> <p>UART/synchronous interface selective: 3</p>	
I/O Pins	I/O	58 • Common use
A/D Inputs	10-bit × 8-ch.	
Electrical Characteristics	T.B.D.	

Pin Assignment



LQFP80-P-1414A^{Pb-free}

SupportTool

In-circuit Emulator	PX-ICE103S53	
On-board Development Tools	PX-ODB103S-O	
Flash Memory Built-in Type	Type	MN103SF53G (under development)
	Command ROM (× 64-bit)	128 K-byte
	Data RAM (× 32-bit)	12 K-byte
	Minimum instruction execution time	25.0 ns (at 3.0 V to 3.6 V, 40 MHz)
	Package	LQFP80-P-1414A ^{*Pb-free}

Request for your special attention and precautions in using the technical information and semiconductors described in this material

- (1) An export permit needs to be obtained from the competent authorities of the Japanese Government if any of the products or technical information described in this material and controlled under the "Foreign Exchange and Foreign Trade Law" is to be exported or taken out of Japan.
- (2) The technical information described in this material is limited to showing representative characteristics and applied circuits examples of the products. It neither warrants non-infringement of intellectual property right or any other rights owned by our company or a third party, nor grants any license.
- (3) We are not liable for the infringement of rights owned by a third party arising out of the use of the technical information as described in this material.
- (4) The products described in this material are intended to be used for standard applications or general electronic equipment (such as office equipment, communications equipment, measuring instruments and household appliances).
Consult our sales staff in advance for information on the following applications:
 - Special applications (such as for airplanes, aerospace, automobiles, traffic control equipment, combustion equipment, life support systems and safety devices) in which exceptional quality and reliability are required, or if the failure or malfunction of the products may directly jeopardize life or harm the human body.
 - Any applications other than the standard applications intended.
- (5) The products and product specifications described in this material are subject to change without notice for modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date Product Standards in advance to make sure that the latest specifications satisfy your requirements.
- (6) When designing your equipment, comply with the guaranteed values, in particular those of maximum rating, the range of operating power supply voltage, and heat radiation characteristics. Otherwise, we will not be liable for any defect which may arise later in your equipment.
Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- (7) When using products for which damp-proof packing is required, observe the conditions (including shelf life and amount of time let standing of unsealed items) agreed upon when specification sheets are individually exchanged.
- (8) This material may be not reprinted or reproduced whether wholly or partially, without the prior written permission of Matsushita Electric Industrial Co., Ltd.